

Amendments to the Specification:

Please amend the paragraph beginning on page , line as shown below.

Please amend paragraph [] as shown below.

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Please amend paragraph [0034] as follows:

[0034] The silicone resin can be any alkyl and/or aryl substituted polysiloxane, copolymer, blend or mixture thereof. Examples of a silicone resin include ultraviolet (UV) curable sol-gels, UV curable epoxy silicone, UV curable acrylate silicone, and UV curable silicone via thiolene chemistry; and non-cured materials such as hydrogen silsesquioxane, and poly(meth)acrylate/siloxane copolymers.

Silsesquioxanes, or T-resins, having a general repeating unit with a formula: $RSiO_{1.5}$. Preferably, a hydroxyl-functional polysiloxane is used such as a hydroxyl-functional organo-siloxane, with examples of organo-siloxanes including methyl, phenyl, propyl and their mixtures. The silicone resin may be present in the silicon-containing composition in amounts of approximately 2 to 40% by weight, depending on the thicknesses desired for conformal layer 58. An exemplary example of a hydroxyl-functional polysiloxane used in the present invention is a silicon T-resin intermediate available from Dow Corning® (Midland, Michigan) under the trade name Z-6018.

Please amend paragraph [0035] as follows:

[0035] The cross-linking agent is a compound that includes two or more polymerizable groups. The cross-linking agent may be present in the silicon-containing composition in amounts of approximately 2 to 50% by weight in relation to the quantity of silicone resin present. Typically, the cross-linking agent is present in the silicon-containing composition in an amount of approximately 20 to 30%. An ~~exemplary~~ example of a cross-linking agent used in the present invention is a hexamethoxymethylmelamine(HMMM) based aminoplast cross-linking agent available from Cytec Industries, Inc. (West Paterson, New Jersey) under the trade name CYMEL 303ULF.

Please amend paragraph [0036] as follows:

[0036] The catalyst may be any component that catalyzes a condensation reaction. Suitable catalysts may include, but are not limited to, acidic compounds such as sulfonic acid. The catalyst may be present in the silicon-containing material in amounts of approximately 0.05% to 5% by weight in relation to the silicone resin present. Typically, the catalyst is present in the silicon-containing material in an amount of approximately 1 to 2%. An ~~exemplary~~ example of a catalyst used in the present invention is toluenesulfonic acid available from Cytec Industries, Inc. (West Paterson, New Jersey) under the trade name CYCAT 4040.

Please amend paragraph [0037] as follows:

[0037] For the balance of the composition, a solvent is utilized. The solvent can be any solvent or combination of solvents that satisfies several criteria. As mentioned above, the solvent should not cause solidified imprinting layer 134 to swell. In addition, the evaporation rate of the solvent should be established so that a desired quantity of the solvent evaporates as a result of the spin-coating process while providing sufficient viscosity to facilitate planarization of silicon-containing material in furtherance of forming conformal layer 58. Suitable solvents may include, but are not limited to, alcohol, ether, a glycol or glycol ether, a ketone, an ester, an acetate and mixtures thereof. The solvent may be present in the silicon-containing material used to form conformal layer 58 in amounts of approximately 60 to 98% by weight, dependent upon the desired thicknesses of conformal layer 58. An exemplary example of a solvent used in the present invention is methyl amyl ketone available from Aldrich Co. (St. Louis, Missouri) under the trade name MAK.

Please amend paragraph [0038] as follows:

[0038] In a further embodiment, the composition of conformal layer 58 is altered to include an epoxy-functional silane coupling agent to improve the cross-linking reaction and improve the rate of cross-linking. Examples of epoxy-functional silanes may include

glycidoxymethyltrimethoxysilane, 3-
glycidoxypropyltrihydroxysilane, 3-
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glycidoxypropyltrimethoxysilane, 2,3-
epoxypropyltrimethoxysilane, and the like. The epoxy-functional silane may be present in conformal layer 58 in amounts of approximately 2 to 30% by weight of silicon-containing compound in relation to the silicone resin and typically in an amount of 5 to 10%. An exemplary example of epoxy-functional silane used in the present invention is gamma-glycidoxypropyltrimethoxysilane available from GE Silicone/OSi Specialty (Wilton, CT) under the trade name A187.